

MAP 2011 Program Overview

Tuesday 1 th November, 2011		
Time	Excursion	
10:00~11:30	Research Center for Three-Dimensional Semiconductors	
Time	Presentation @Navis A	Exhibition @Navis B & C
13:00 ~ 13:05	Opening Remark	Poster & Exhibition
13:05 ~ 14:45	Session 1: Invited Talks	
14:45 ~ 15:20	Coffee Break	
15:20 ~ 17:25	Session 2: Device Embedded Substrate	
17:30 ~ 19:00	Poster Session with Wines (Reception Party) @Navis B & C	
Wednesday 2 th November, 2011		
09:00 ~ 10:50	Session 4: International R&D Perspective Regional Innovation Cluster Program 【Global Type(2nd Stage) Expansion Program Workshop】	Poster & Exhibition
10:50 ~ 11:15	Coffee Break	
11:15 ~ 12:20	Session 5: 3D Integration Technology Regional Innovation Cluster Program 【Global Type(2nd Stage) Expansion Program Workshop】	
12:15 ~ 13:00	Lunch Break	
13:00 ~ 14:40	Session 6: Indian Session	
14:40 ~ 15:15	Coffee Break	
15:15 ~ 17:20	Session 7: Assembling Technology	
17:20 ~ 17:25	Closing Remark	

MAP2011 Program

Tuesday 1st, November

13:00 ~ 13:05 Opening Remark

Chair: Hajime Tomokage

Fukuoka University (JAPAN)

13:05 ~ 14:45 Session 1: Invited Talks

Chair: Joseph Fejelstad

Verdant Electronics (U.S.A.)

13:05-13:55 1-1 High Performance, Low Pin Count Packaging

Charles E. Bauer

TechLead Corporation (U.S.A.)

13:55-14:45 1-2 A Dawn of Small Electrical Aircraft

Shigeru ASO

Kyushu University (JAPAN)

14:45 ~ 15:20 Coffee Break

15:20-17:25 Session 2: Device Embedded Substrate

Chair: Wei-Chung Lo

Industrial Technology Research Institute(ITRI) (TAIWAN, R.O.C)

15:20-15:45 2-1 Standardization Activities in Three Dimensional Jisso Technology

Masamitsu Aoki

Japan Electronics Packaging and Circuits Association (JPCA) (JAPAN)

15:45-16:10 2-2 New Data Format FUJIKO for Device Embedded Substrate

Hidemichi Kawase

Keirex Technology Inc. (JAPAN)

16:10-16:35 2-3 New Design Method of Embedded Components in the New Generation PCB CAD System

Kazuhiro Kariya

Zuken Inc. (JAPAN)

16:35-17:00 2-4 Advanced Materials for PKG Substrate

Makoto Kato

Hitachi Chemical Co., Ltd. (JAPAN)

17:00-17:25 2-5 Challenges in Testing Embedded Passive and Active Devices

Hiroshi Yamazaki

HIOKI E.E. CORPORATION (JAPAN)

17:30 ~ 19:00 Poster Session with Wines (Reception Party) @Navis B & C

Chair: Dorai Arasu

InfoSree Technologies Pvt. Ltd. (INDIA)

Wednesday 2th, November

09:00 ~ 10:50 Session 4: International R&D Perspective

Regional Innovation Cluster Program 【Global Type(2nd Stage) Expansion Program Workshop】

Chair: Eddie Ohturu

Fukuoka Industry, Science and Technology Foundation (JAPAN)

- 09:00-09:40 4-1 Multi-Dimension Integration with TSVs and Microbumps
Wei-Chung Lo
Industrial Technology Research Institute(ITRI) (TAIWAN, R.O.C)
- 09:40-10:10 4-2 Wafer Bonding as a Key Technology for 3D Integration of MEMS and Electronics
Jörg Frömel
Fraunhofer ENAS (GERMANY)
- 10:10-10:50 4-3 An Efficient Fab Operation and Equipment Analysis Systems to Improve Productivity in Semiconductor Manufacturing Line
Jinki Kim
Samsung Electronics Co., Ltd. (KOREA)

10:50 ~ 11:15 Coffee Break

11:15 ~ 12:20 Session 5: 3D Integration Technology

Regional Innovation Cluster Program 【Global Type(2nd Stage) Expansion Program Workshop】

Chair: Akihiro Kawaguchi

Fukuoka Industry, Science and Technology Foundation (JAPAN)

- 11:15-11:30 5-1 3D Package Technology – History and Future
Akito Yoshida
Amkor Technology, Inc. (U.S.A.)
- 11:30-11:55 5-2 Sidewall Insulator Film Deposition for the Through Silicon Via (TSV) Process Using Cathode Coupled PE-CVD
Yutaka Kusuda
SAMCO Inc. (JAPAN)
- 11:55-12:20 5-3 Reliability - Cornerstone of Sustainable Electronic Manufacturing
Joseph Fejelstad
Verdant Electronics (U.S.A.)

12:20 ~ 13:00 Lunch Break

13:00 ~ 14:40 Session 6: Indian Session

Chair: Daisuke Yamaguchi

Asia Semiconductor Trading Support Association (JAPAN)

- 13:00-13:25 6-1 TCS Semiconductor Engineering Services
Simon Johney
Tata Consultancy Services Limited (INDIA)
- 13:25-13:50 6-2 Materials and Nanotechnology Driving the Future of Electronics Industry
Sudhanshu Misra
Excel Industries, Limited (INDIA)
- 13:50-14:15 6-3 Design of Low Cost Car Infotainment Solution
Mihir Kumar Sahu
VINJEY Software Systems Pvt. Ltd. (INDIA)
- 14:15-14:40 6-4 Engineering Services for Semiconductor Equipment Industry
Susanta Panigrahy
HCL Technologies Limited (INDIA)

14:40 ~ 15:15 Coffee Break

15:15 ~ 17:20 Session 7: Assembling Technology

Chair: Seiichiro Yoshida

New Japan Radio Co., Ltd. (JAPAN)

- 15:15-15:40 7-1 Merged Production of Bare Dies and SMDs
Tomohiko Hattori
Fuji Machine Manufacturing Co., Ltd. (JAPAN)
- 15:40-16:05 7-2 Investigation of Detailed Models and Simplification in Thermal Analyses of Electronic Devices
Jun Eto
Software Cradle Co., Ltd. (JAPAN)
- 16:05-16:30 7-3 Value-added Solutions for High-quality, Low-cost Production of Devices -LED Package-
Mitsuru Ozono
Panasonic Factory Solutions Co., Ltd. (JAPAN)
- 16:30-16:55 7-4 High Reliability Ceramic Packaging Capability
Paddy Hiroshi Ohhara
Millennium Microtech Holding Corporation (JAPAN)
- 16:55-17:20 7-5 Inspection and Metrology Challenges in 3D IC Technology
Eric Bouche
KLA-Tencor Corporation (U.S.A.)

17:20 ~ 17:25 Closing Remarks

Chair: Hajime Tomokage

Fukuoka University (JAPAN)

MAP2011 Program Poster Exhibition

Tuesday 1th- Wednesday 2th, November

Industrial Technology Research Institute(ITRI)(Taiwan, R.O.C)

TechLead Corporation(U.S.A.)

InfoSree Technologies Pvt. Ltd.(INDIA)

Vinje Software Systems Pvt., Ltd.(INDIA)

Excel Industries Limited(INDIA)

PMT Corporation(JAPAN)

MiS Technologies Corporation(JAPAN)

Shintec Co., Ltd.(JAPAN)

Advantest Corporation(JAPAN)

WALTS Co., Ltd.(JAPAN)

Inoueki,. Co. Ltd.(JAPAN)

Espec Kyushu Corp.(JAPAN)

ELIA Co., Ltd.(JAPAN)

Senju Metal Industry Co., Ltd.(JAPAN)

Fukuoka Industry, Science & Technology Foundation(JAPAN)

Solar Network In Q-shu(JAPAN)

Fraunhofer ENAS Chemnitz(GERMANY)

Verdant Electronics(U.S.A.)

HCL Technologies Ltd.(INDIA)

TATA Consultancy Services Limited(INDIA)

Aska Plating Corporation(JAPAN)

Zuken Inc.(JAPAN)

Adwelds Corporation(JAPAN)

SAMCO Inc.(JAPAN)

Tokuyama Corporation(JAPAN)

Echigo Fudagami Co., Ltd.(JAPAN)

Software Cradle Co., Ltd.(JAPAN)

Fuji Machine Mfg. Co., Ltd.(JAPAN)

Nikon Tec Corporation(JAPAN)

BEAMSENSE Co., Ltd.(JAPAN)

Dempa Publication, Inc.(JAPAN)